60 V

0.68 V



advanced

Schottky

High Performance Schottky Diode Low Loss and Soft Recovery Common Cathode

Part number (Marking on product)

DSA 20 C 60PN

1 3

Features / Advantages:

- Very low Vf
- Extremely low switching losses
- Low Irm-values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters



Package:

 $V_{RRM} =$

 $I_{FAV} = 2x \cdot 10 A$

TO-220FPAB

- Industry standard outline
- Plastic overmolded tab for electrical isolation
- Epoxy meets UL 94V-0
- RoHS compliant

Ratings

Definition	Conditions		min.	typ.	max.	Unit
max. repetitive reverse voltage		T _{vJ} = 25 °C			60	V
reverse current	V _R = 60 V	T _{VJ} = 25 °C			0.3	mA
	$V_R = 60 V$	T_{VJ} = 125 °C			3	mA
forward voltage	I _F = 10 A	T _{VJ} = 25°C			0.85	V
	$I_F = 20 A$				0.95	V
	$I_F = 10 A$	T 405 %O			0.68	V
	$I_{F} = 20 \text{A}$	1 _{VJ} = 125 C			0.78	V
average forward current	rectangular, d = 0.5	$T_c = 140 ^{\circ}C$			10	Α
threshold voltage	calculation only $T_{VJ} = 175 ^{\circ}\text{C}$			0.44	V	
slope resistance				15	mΩ	
thermal resistance junction to case					4.50	K/W
virtual junction temperature			-55		175	°C
total power dissipation		T _C = 25 °C			35	W
max. forward surge current	$t_p = 10 \text{ ms } (50 \text{ Hz}), \text{ sine}$	T _{VJ} = 45 °C			100	Α
junction capacitance	$V_R = V; f = 1 MHz$	$T_{VJ} = 25 ^{\circ}C$				pF
non-repetitive avalanche energy	$I_{AS} = A; L = 100 \mu H$	$T_{VJ} = 25 ^{\circ}C$			tbd	mJ
repetitive avalanche current	$V_A = 1.5 \cdot V_R \text{ typ.; } f = 10 \text{ kHz}$				tbd	Α
	max. repetitive reverse voltage reverse current forward voltage average forward current threshold voltage slope resistance thermal resistance junction to case virtual junction temperature total power dissipation max. forward surge current junction capacitance non-repetitive avalanche energy	$ \begin{array}{llllllllllllllllllllllllllllllllllll$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$



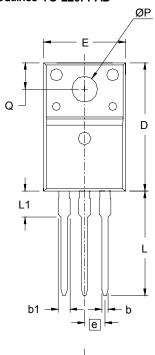
advanced

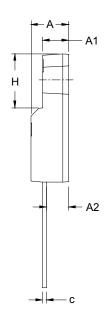
Ratings	

Symbol	Definition	Conditions	min.	typ.	max.	Unit
I _{RMS}	RMS current	per pin*			35	Α
R _{thCH}	thermal resistance case to I	neatsink		0.50		K/W
M _D	mounting torque		0.4		0.6	Nm
F _c	mounting force with clip		20		60	N
T _{stg}	storage temperature		-55		150	°C
Weight				2		g

^{*} Irms is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip. In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

Outlines TO-220FPAB





SYM	INCHES		MILLIMETERS		
2114	MIN	MAX	MIN	MAX	
Α	.177	.193	4.50	4.90	
A1	.092	.108	2.34	2.74	
A2	.101	.117	2.56	2.96	
b	.028	.035	0.70	0.90	
b1	.050	.058	1.27	1.47	
С	.018	.024	0.45	0.60	
D	.617	.633	15.67	16.07	
E	.392	.408	9.96	10.36	
е	.100 BSC		2.54 BSC		
Н	.255	.271	6.48	6.88	
L	.499	.523	12.68	13.28	
L1	.119	.135	3.03	3.43	
ØΡ	.121	.129	3.08	3.28	
Q	.126	.134	3.20	3.40	